

Wiring, Printed – Component

COMPANY

HUADING GROUP CO LTD

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E347973

Type	Cond Width				Max Area Diam	Report date After 2022-01-01	Surface Mount Technology	Assembly Solder				Solder		Max Oper		Meets UL796 DSR	C T
	Min	Edge	Cond Thk	SS/DSO				Process	Process	Limits	Temp	Flame					
	mm	mm	mic	DSO				mm	Temp °C	Cycles	°C	sec	°C	Class			
	mm	mm	mic	DSO				mm	Temp °C	Cycles	°C	sec	°C	Class			
Metal Base Single Layer Printed Wiring Boards with Flammability Only Recognition																	
HD-MC04	-	-	-	SS	-	No	-	-	-	288	10	-	V-0	-	-	-	
Multilayer printed wiring boards																	
HD-03	0.15	0.45	17 Int:35	DS	25.4	No	-	-	-	260	10	105	V-0	All	-	-	
HD-05	0.1	0.1	17 Int:68	DS	50.8	No	-	-	-	288	20	130	V-0	All	1	1	
HD-06	0.075	0.075	17 Int:68	DS	50.8	No	-	-	-	288	20	130	V-0	All	3	3	
HD-M02	0.1	0.3	17 Int:24	DS	25	No	-	-	-	250	10	130	V-0	All	*	*	
HD-M12	0.1	0.1	18 Int:70	DS	25.4	No	-	-	-	280	10	130	V-0	All	*	*	
HD-M13 (ASP 1)	0.1	0.1	18 Int:70	DS	25.4	Yes	Yes	260	3	-	-	130	V-0	All	*	*	
HD-M20	0.075	0.2	17 Int:70	DS	50.8	No	-	-	-	288	20	110	V-0	All	*	*	
HD-M21	0.15	0.25	17 Int:70	DS	50.8	No	-	-	-	288	20	130	V-0	All	*	*	
HD-M22	0.1	0.1	12 Int:70	DS	50.8	No	-	-	-	288	20	130	V-0	All	*	*	

译

AI翻译

目标语言：

简体中文

翻译模型：

经典翻译

译文模式：

仅译文

PDF 翻译

HD-M26	0.08	0.24	17 Int:102	DS	76.2	No	-	-	-	288	20	130	V-0	All	*
HD-M27	0.08	0.08	12 Int:70	DS	25.4	No	-	-	-	288	10	130	V-0	All	*
HD-M28	0.35	0.35	17 Int:175	DS	50.8	No	-	-	-	255	5	130	V-0	All	*
HD-M29	0.25	0.3	17 Int:212	DS	50.8	No	-	-	-	288	10	130	V-0	All	*
HD-M30	0.25	0.3	17 Int:212	DS	50.8	No	-	-	-	288	10	130	V-0	All	*
HD-M31	0.08	0.24	17 Int:34	DS	50.8	No	-	-	-	260	10	130	V-0	All	*
HD-M32	0.08	0.1	17 Int:60	DS	50.8	No	-	-	-	288	20	130	V-0	All	4
HD-M33	0.05	0.05	10 Int:102	DS	76.2	No	-	-	-	280	20	130	V-0	All	*
HD-M34	0.05	0.05	10 Int:102	DS	76.2	No	-	-	-	280	20	130	V-0	All	*
HD-M35	0.05	0.05	10 Int:68	DS	76.2	No	-	-	-	280	20	130	V-0	▲	3
HD-M36 (ASP 1)	0.05	0.05	10 Int:68	DS	76.2	Yes	Yes	260	6	-	-	130	V-0	All	3
HD-M37	0.05	0.05	10 Int:68	DS	152.4	No	-	-	-	288	20	130	V-0	All	*
HD-M38	0.05	0.05	10 Int:68	DS	152.4	No	-	-	-	288	20	130	V-0	All	*
HD-M39	0.05	0.05	10 Int:68	DS	152.4	No	-	-	-	288	20	130	V-0	All	*
HD-M40	0.05	0.05	10 Int:68	DS	76.2	No	-	-	-	280	20	130	V-0	All	3
HD-M41	0.05	0.05	10 Int:68	DS	76.2	No	-	-	-	280	20	130	V-0	All	2
HD-M42	0.05	0.05	10 Int:68	DS	76.2	No	-	-	-	280	20	130	V-0	All	2
HD-M43	0.05	0.05	10 Int:102	DS	76.2	No	-	-	-	280	20	130	V-0	All	*
HD-M44	0.05	0.05	10 Int:68	DS	76.2	No	-	-	-	280	20	130	V-0	All	2
HD-	0.05	0.05	10	DS	152.4	No	-	-	-	288	20	130	V-0	All	*

(ASP 1)															
HD-S18	0.15	0.15	34	SS	25.4	No	-	-	-	288	10	130	V-0	All	*
HD-S26	0.15	0.15	34	SS	25.4	No	-	-	-	288	10	130	V-0	All	*

Single Layer Printed Wiring Boards Flammability Only Recognition															
HD-D17	-	-	-	DS	-	No	-	-	-	288	20	-	V-0	-	*

Single layer printed wiring boards, flammability only Recognition															
HD-01	-	-	-	DS	-	No	-	-	-	288	15	-	V-0	-	-
HD-D05	-	-	-	DS	-	No	-	-	-	265	5	-	V-0	-	-
HD-D10	-	-	-	DS	-	No	-	-	-	280	10	-	V-0	-	-
HD-D11	-	-	-	DS	-	No	-	-	-	280	10	-	V-0	-	-
HD-D12	-	-	-	DS	-	No	-	-	-	280	10	-	V-0	-	-
HD-D13	-	-	-	DS	-	No	-	-	-	280	10	-	V-0	-	-
HD-D14	-	-	-	DS	-	No	-	-	-	280	10	-	V-0	-	-
HD-S05	-	-	-	SS	-	No	-	-	-	260	10	-	V-1	-	-
HD-S10	-	-	-	SS	-	No	-	-	-	260	10	-	V-0	-	-

* - CTI marking is optional and may be marked on the printed wiring board.

(ASP 1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Note 1 - Minimum conductor width and edge conductor width is 0.075mm when external copper thickness is 12-102mic.
Minimum conductor width and edge conductor width is 0.25mm when external copper thickness is 103-140mic.

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